

In the Specification:

Please amend paragraph 1 as follows:

This application is related to U.S. Patent Application No. ~~(Attorney Docket No. 10829.8742US00; Micron Disclosure Nos. 03-0599 and 03-0613)~~10/713,878 entitled MICROELECTRONIC DEVICES, METHODS FOR FORMING VIAS IN MICROELECTRONIC DEVICES, AND METHODS FOR PACKAGING MICROELECTRONIC DEVICES, filed ~~concurrently herewith~~November 13, 2003, and incorporated herein in its entirety by reference.